LOTTE CHEMICAL

HOPELEX AN-3700

PC/ABS alloy resin

General information

Description

PC/ABS with balanced flowability, impact properties and hydrolytic stability
Non-brominated, non-chlorinated flame retardant

Applications

Wide variety of applications with OA and electronic housings

Typical properties[1]

	Test method	Typical value	Unit
Physical			
Melt Flow Index, 260°C, 5 kg	ASTM D1238	**-**	g/10 min
Specific Gravity	ASTM D792	**1.2**	
Mold Shrinkage	ASTM D955	**0.4~0.6**	%
Mechanical			
Tensile Strength, yield, 50 mm/min	ASTM D638	**590**	kg_f/cm^2
Tensile Elongation, break, 50 mm/min	ASTM D638	**> 100**	%
Flexural Strength, yield, 10 mm/min	ASTM D790	**880**	kg_f/cm^2
Flexural Modulus, 10 mm/min	ASTM D790	**25,000**	kg_f/cm^2
IZOD Impact Strength, notched, 23°C, 1/8”	ASTM D256	**50**	kg_f·cm/cm
notched, 23°C, 1/4”	ASTM D256	**-**	kg_f·cm/cm
notched, -30°C, 1/8”	ASTM D256	**-**	kg_f·cm/cm
Thermal			
Heat Distortion Temp. 4.6 kg_f/cm^2	ASTM D648	**-**	°C
18.6 kg_f/cm^2	ASTM D648	**80**	°C
Vicat Softening Temp. Rate B/50	ASTM D1525	**-**	°C
Flammability			
V-0	Lotte Chemical Method	**1.5**	mm

Notes

ISO 9001, 14001, TS 16949

[1] Typical properties : these are not to be construed as specifications.

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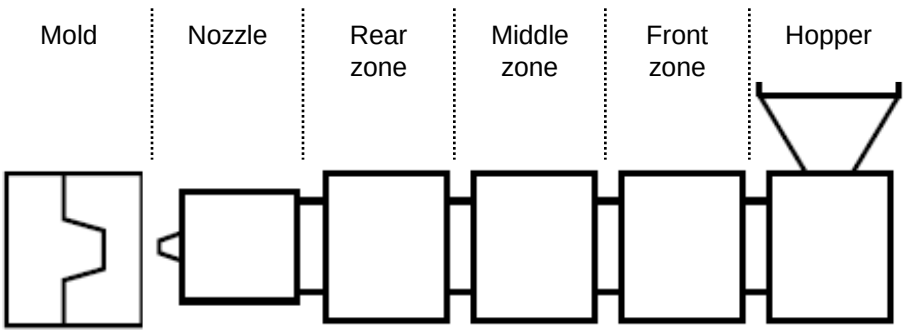
Processing guides[1]

		Typical value	Unit
Drying condition			
Drying temperature		**80 ~ 90**	°C
Drying time		**4**	hr
Maximum moisture content		**0.02**	%
Injection molding			
Melt temperature		**240 ~ 260**	°C
Nozzle temperature		**240 ~ 260**	°C
Barrel	**Rear zone**	**240 ~ 260**	°C
	Middle zone	**230 ~ 250**	°C
	Front zone	**220 ~ 240**	°C
Hopper temperature		**60 ~ 80**	°C
Mold temperature		**60 ~ 80**	°C



Recycling

Sprues and runners can be reground with virgin resin within the ratio of 20%. Care must be taken to ensure that the regrind is free from impurities and regrind should not be used in applications where impact performance and/or agency compliance are required.

Notes

ISO 9001, 14001, TS 16949

[1] Processing guides : Typical processing parameters are noted. Actual processing conditions will depend on machine size, mold design, material residence time, shot size, etc.